ASSOCIATION CONNECTING ELECTROWICS INDUSTRIES® OCOPYTIGHT 2005. Il international and Pan	o sition De PC, Bannock American c	claration burn, Illinois. A opyright conver	ll rights reserved ntions.	under both						in the manufactuel materials for v					
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
upplier Information															
Company name* Company unique ID				1	Unique ID Authority					Response Date*					
ısemi						2023-06-08									
Contact Name Title - Contact]	Phone - Contact*					Email - Contact*				
Product-Env-Stewards	ro Compliance		NA				Produc	Product-Env-Stewards@onsemi.com							
Authorized Representative* Title - Representative			sentative]	Phone - Representative*					Email - Representative*				
roduct-Env-Stewards	Product Enviro Compliance				NA				Produc	Product-Env-Stewards@onsemi.com					
Requester Item Number Mfr Iter		Number Mfr Item Name			Effective Da	ate Ve	Version Manufacturing Site		1	Weight*	* [L	JOM	Unit Type		
	AR0331 A0-DPE	BISRSC00SUC 3.1 MP 1/3 CIS				2023-06-08		TA1		2	252.49 mg		ng	Each	
Ianufacturing Proccess Informat	tion						·								
Terminal Plating / Grid Array Ma	terial	Terminal Base Alloy		J-STD-020 MS	SL Rating	Peak Pr	Process Body Temperature Max Time at Pea		k Temperat	Temperature Number of Reflow Cycles		les			
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy	Alloy 4			260 C		3	0	secon	ds 3				
omments								•							
or more information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed								
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	HS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl halate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of								
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted								
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all								
Exemption List Version	EL-2011/534/EU												
Declaration Signature													
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the								
Supplier Digital Signature Ra	stislav Drska	Le											

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	57.0	mg		Misc.	proprietary data		0.2166	mg
			Supplier	Silicon (Si)	7440-21-3		56.2191	mg
			Supplier	Aluminum (Al)	7429-90-5		0.5643	mg
Die Attach	1.85	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.6938	mg
			Supplier	Ethylene Glycol	107-21-1		0.0185	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.0555	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.3885	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.6938	mg
Imaging Lens	51.13	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		2.691	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		2.691	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		2.691	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.2695	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.691	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		2.691	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		37.4057	mg
Lid Attach	2.45	mg	Supplier	2-phenoxy ethyl acrylate	48145-04-6		1.1025	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.49	mg
			Supplier	Filler (SiO2)	68909-20-6		0.3063	mg
			Supplier	Acrylate Oligomer	Proprietary Data		0.0122	mg
			Supplier	Curative	Proprietary Data		0.049	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.49	mg
Mold Compound-Black	55.9	mg		Phenolic Resin	proprietary data		8.385	mg
			Supplier	Oxirane	39817-09-9		8.385	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.677	mg
			Supplier	Carbon Black (C)	1333-86-4		0.559	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		35.776	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.118	mg
Substrate and Solder Mask	83.88	mg	Supplier	Acetophenone	98-86-2		1.644	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		18.613	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		1.0988	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.1072	mg

			Supplier	Carbon Black (C)	1333-86-4	0.2768	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2768	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.2881	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	8.388	mg
			Supplier	Copper (Cu)	7440-50-8	40.6818	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	8.5054	mg
Wire Bond - Au	0.28	mg	Supplier	Gold (Au)	7440-57-5	0.28	mg